

# **Small Outline Optoisolators**

# **Transistor Output**

These devices consist of a gallium arsenide infrared emitting diode optically coupled to a monolithic silicon phototransistor detector, in a surface mountable, small outline, plastic package. They are ideally suited for high density applications, and eliminate the need for through—the—board mounting.

- Convenient Plastic SOIC-8 Surface Mountable Package Style
  - Standard SOIC-8 Footprint, with 0.050 Lead Spacing
- · Compatible with Dual Wave, Vapor Phase and IR Reflow Soldering
- High Input-Output Isolation of 3000 Vac (rms) Guaranteed
- • UL Recognized File #E90700, Volume 2

#### **Ordering Information:**

- •To obtain MOC211, 212 and 213 in Tape and Reel, add R2 suffix to device numbers: R2 = 2500 units on 13" reel
- •To obtain MOC211, 212 and 213 in quantities of 50 (shipped in sleeves) No Suffix

#### **Marking Information:**

- • MOC211 = 211
- • MOC212 = 212
- • MOC213 = 213

#### **Applications:**

- General Purpose Switching Circuits
- Interfacing and coupling systems of different potentials and impedances
- Regulation Feedback Circuits
- • Monitor and Detection Circuits

## **MAXIMUM RATINGS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

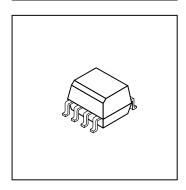
Symbol	Value	Unit
ΙF	60	mA
I <sub>F</sub> (pk)	1.0	Α
٧R	6.0	V
PD	90 0.8	mW mW/°C
	I <sub>F</sub> I <sub>F</sub> (pk) V <sub>R</sub>	IF 60 IF(pk) 1.0 VR 6.0 PD 90

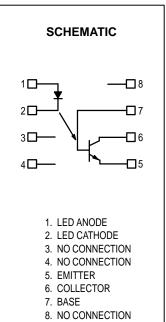
#### **OUTPUT TRANSISTOR**

Collector–Emitter Voltage	VCEO	30	V
Collector–Base Voltage	VCBO	70	V
Emitter–Collector Voltage	VECO	7.0	V
Collector Current — Continuous	IC	150	mA
Detector Power Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	PD	150 1.76	mW mW/°C

MOC211 MOC212 MOC213

SMALL OUTLINE OPTOISOLATORS TRANSISTOR OUTPUT





Value

Unit

Symbol



### MAXIMUM RATINGS — continued (T<sub>A</sub> = 25°C unless otherwise noted)

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TOTAL DEVICE					
Input–Output Isolation Voltage <sup>(1,2)</sup> (60 Hz, 1.0 sec. duration)		VISO	30	3000	
Total Device Power Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C  Ambient Operating Temperature Range <sup>(3)</sup> Storage Temperature Range <sup>(3)</sup> Lead Soldering Temperature (1/16" from case, 10 sec. duration)		PD		250 2.94 -45 to +100 -45 to +125	
		TA	–45 to		
		T <sub>stg</sub>	–45 to		
		<b>—</b> 260		60	°C
ELECTRICAL CHARACTERISTICS (T <sub>A</sub> = 25°C unless otherwis	e noted)(4)	•	•	•	
Characteristic	Symbol	Min	Тур <sup>(4)</sup>	Max	Unit
INPUT LED	•			•	•
Forward Voltage (I <sub>F</sub> = 10 mA)	V <sub>F</sub>	_	1.15	1.5	V
Reverse Leakage Current (V <sub>R</sub> = 6.0 V)	IR	_	0.1	100	μΑ
Capacitance	С	_	18	_	pF
OUTPUT TRANSISTOR					
Collector–Emitter Dark Current $(V_{CE} = 10 \text{ V}, T_A = 25^{\circ}\text{C})$	I <sub>CEO</sub> 1	_	1.0	50	nA
$(V_{CE} = 10 \text{ V}, T_A = 100^{\circ}\text{C})$	I <sub>CEO</sub> 2	_	1.0	_	μΑ
Collector–Emitter Breakdown Voltage ( $I_C = 100 \mu A$ )	V(BR)CEO	30	90	_	V
Emitter–Collector Breakdown Voltage ( $I_E = 100 \mu A$ )	V(BR)ECO	7.0	7.8	_	V
Collector–Emitter Capacitance (f = 1.0 MHz, $V_{CE} = 0$ )	C <sub>CE</sub>	_	7.0	_	pF
COUPLED					_
Output Collector Current MOC211 (IF = 10 mA, V <sub>CE</sub> = 10 V) MOC212 MOC213	I <sub>C</sub> (CTR) <sup>(5)</sup>	2.0 (20) 5.0 (50) 10 (100)	6.5 (65) 9.0 (90) 14 (140)	_ _ _	mA (%)
Collector–Emitter Saturation Voltage (I <sub>C</sub> = 2.0 mA, I <sub>F</sub> = 10 mA)	VCE(sat)	_	0.15	0.4	V
Turn–On Time (I $_{C}$ = 2.0 mA, V $_{CC}$ = 10 V, R $_{L}$ = 100 $\Omega$ )	ton	_	7.5	_	μs
Turn–Off Time (I <sub>C</sub> = 2.0 mA, $V_{CC}$ = 10 V, $R_L$ = 100 $\Omega$ )	t <sub>off</sub>	_	5.7	_	μs
Rise Time (I <sub>C</sub> = 2.0 mA, $V_{CC}$ = 10 V, $R_L$ = 100 $\Omega$ )	t <sub>r</sub>	_	3.2	_	μs
Fall Time (I <sub>C</sub> = 2.0 mA, V <sub>CC</sub> = 10 V, R <sub>L</sub> = 100 $\Omega$ )	t <sub>f</sub>	_	4.7	_	μs
Input–Output Isolation Voltage (f = 60 Hz, t = 1.0 sec.) $(1,2)$	VISO	3000		_	Vac(rms)
Isolation Resistance $(V_{I-O} = 500 \text{ V})(2)$	R <sub>ISO</sub>	10 <sup>11</sup>		_	Ω
Isolation Capacitance $(V_{I-O} = 0, f = 1.0 \text{ MHz})(2)$	C <sub>ISO</sub>	_	0.2	_	pF

- 1. Input–Output Isolation Voltage,  $V_{\mbox{\scriptsize ISO}}$ , is an internal device dielectric breakdown rating.
- 2. For this test, pins 1 and 2 are common, and pins 5, 6 and 7 are common.
- 3. Refer to Quality and Reliability Section in Opto Data Book for information on test conditions.
- 4. Always design to the specified minimum/maximum electrical limits (where applicable).
- 5. Current Transfer Ratio (CTR) = I<sub>C</sub>/I<sub>F</sub> x 100%.



#### **TYPICAL CHARACTERISTICS**

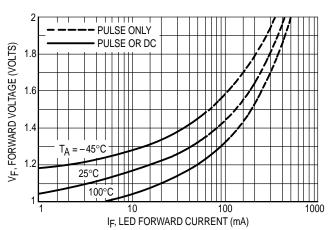


Figure 1. LED Forward Voltage versus Forward Current

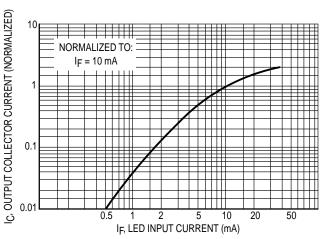


Figure 2. Output Current versus Input Current

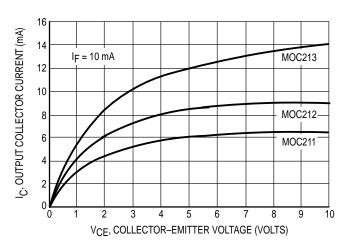


Figure 3. Output Current versus Collector–Emitter Voltage

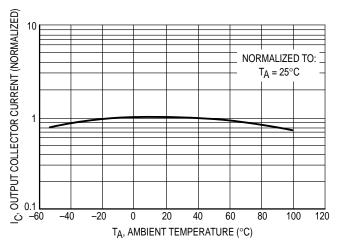


Figure 4. Output Current versus Ambient Temperature

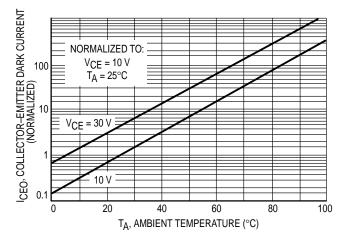


Figure 5. Dark Current versus Ambient Temperature

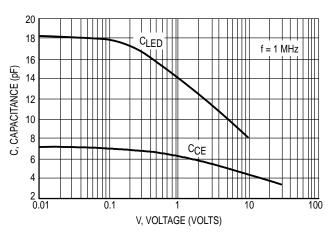
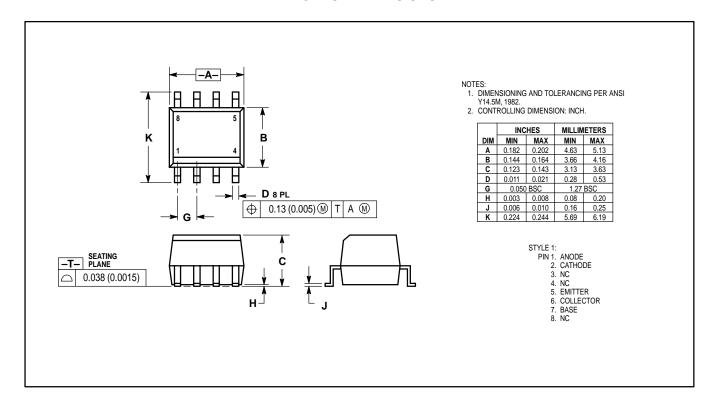


Figure 6. Capacitance versus Voltage



#### **PACKAGE DIMENSIONS**





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